

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
20V	2.2m Ω @10V	80A
	2.5m Ω @4.5V	

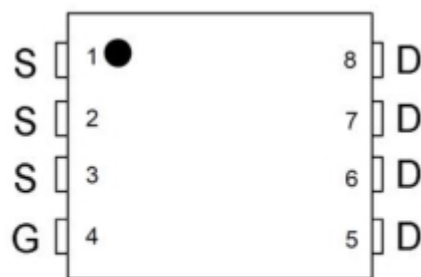
Feature

- $V_{DS} = 20V, I_D = 80A$
- $R_{DS(ON)} < 4.5m\Omega @ V_{GS} = 10V$
- High density cell design for ultra low R_{dson}
- Excellent package for good heat dissipation

Applications

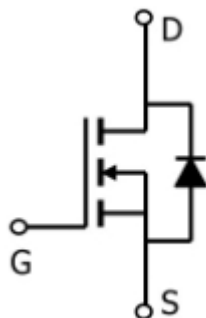
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Package

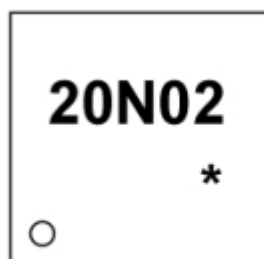


PDFNWB3.3×3.3-8L

Circuit diagram



Marking



20N02 =Device Code
* =Month Code

Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous(T _C = 25°C)	I _D	80	W
Pulsed Drain Current	I _{DM}	320	A
Avalanche Current	I _{AS}	24	A
Single Pulse Avalanche Energy	E _{AS}	144	mJ
Power Dissipation	P _D	85	W
T _C = 25°C			
Thermal Resistance Junction- Case	R _{θJC}	1.47	°C/ W
Operating and Storage Temperature Range	T _J , T _{STG}	-55~ +150	°C

Electrical characteristics

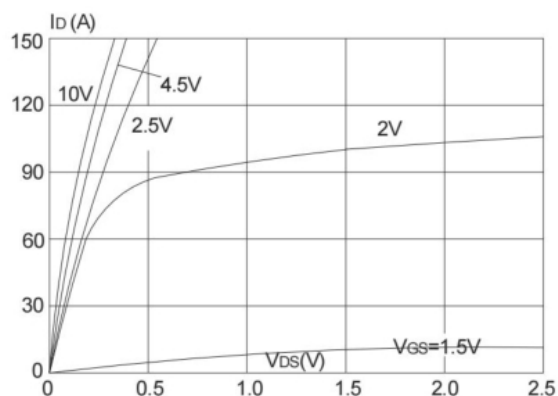
($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$			± 100	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.7	1.1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$		2.2	3	m Ω
		$V_{GS} = 4.5V, I_D = 20A$		2.5	4	
Dynamic characteristics ⁴						
Input Capacitance	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V,$ $f = 1MHz$		5238		pF
Output Capacitance	C_{oss}			932		
Reverse Transfer Capacitance	C_{rss}			833		
Switching Characteristics						
Total Gate Charge(4.5V)	Q_g	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_D = 40A$		55		nC
Gate-Source Charge	Q_{gs}			6.5		
Gate-Drain Charge	Q_{gd}			28		
Turn-On Delay Time	$T_{d(on)}$	$V_{GS} = 4.5V, V_{DD} = 10V,$ $I_D = 40A, R_L = 1\Omega,$ $R_{GEN} = 3\Omega$		8		nS
Rise Time	T_r			26		
Turn-Off Delay Time	$T_{d(off)}$			55		
Fall Time	T_f			35		
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$I_S = 1A, V_{GS} = 0V$			1.2	V

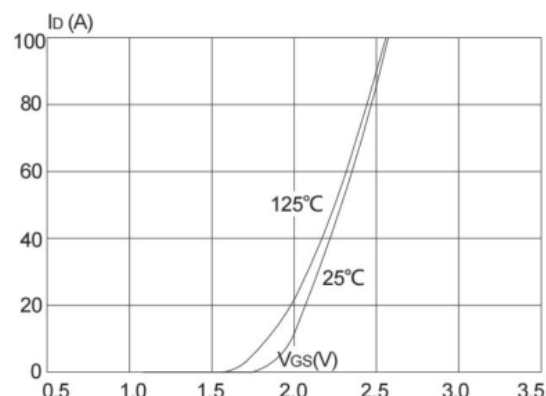
Note :

1. The test condition is $V_{DD}=20V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$

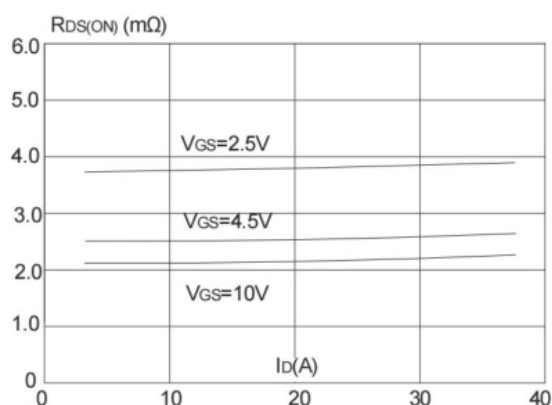
Typical Characteristics



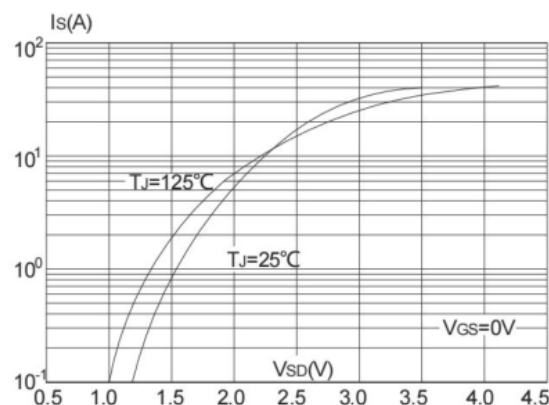
Output Characteristics



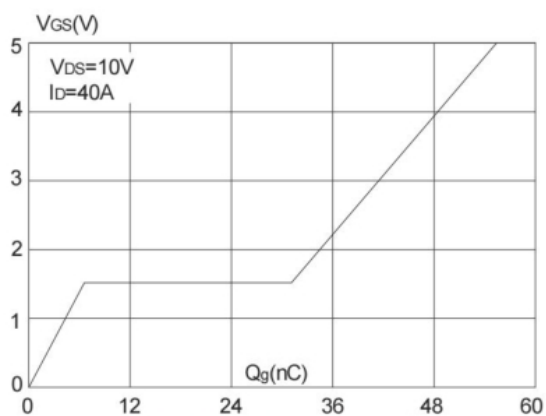
Typical Transfer Characteristics



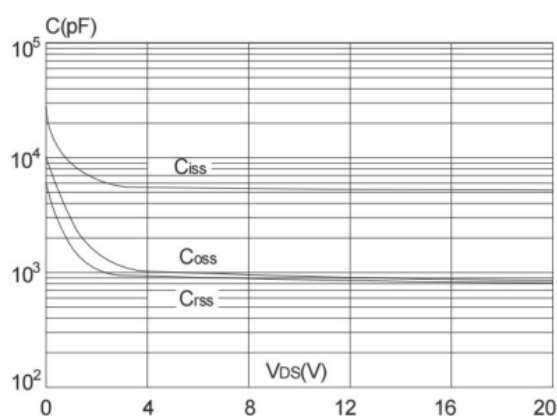
On-resistance vs. Drain Current



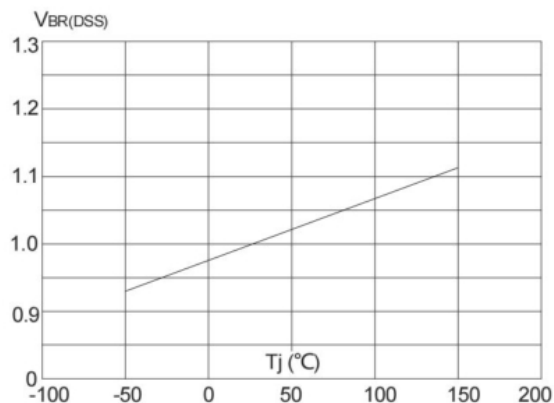
Body Diode Characteristics



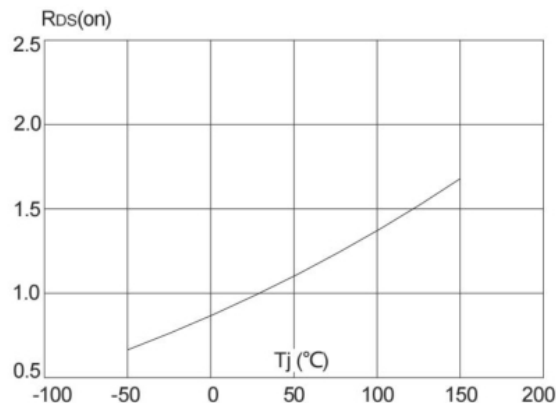
Gate Charge Characteristics



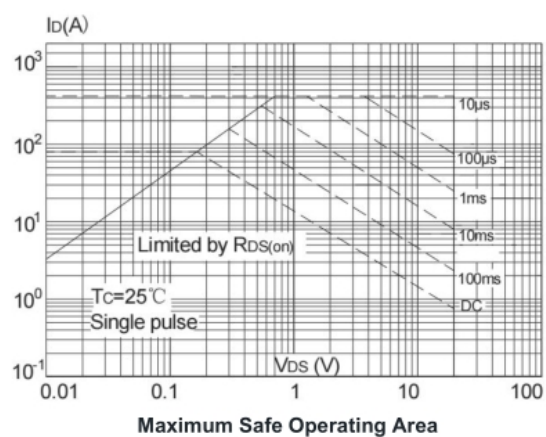
Capacitance Characteristics



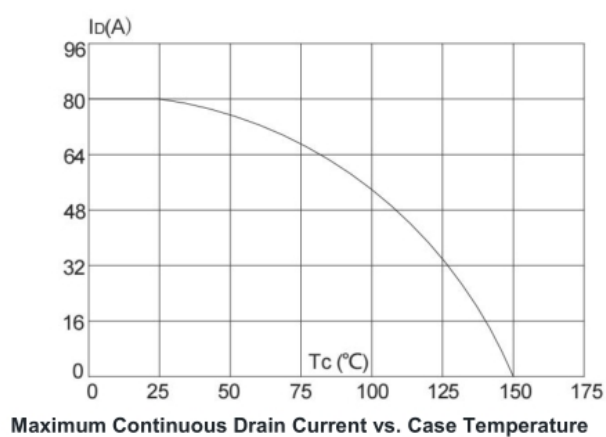
Normalized Breakdown Voltage vs. Junction Temperature



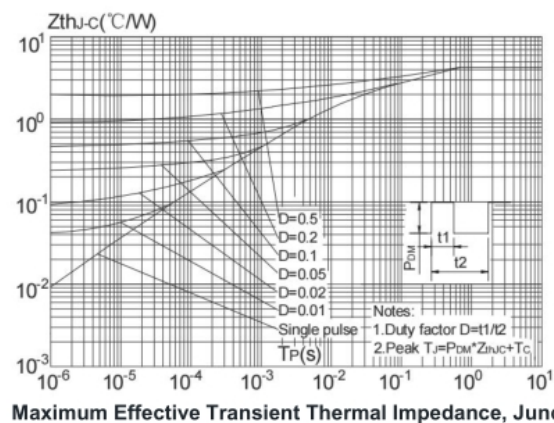
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area

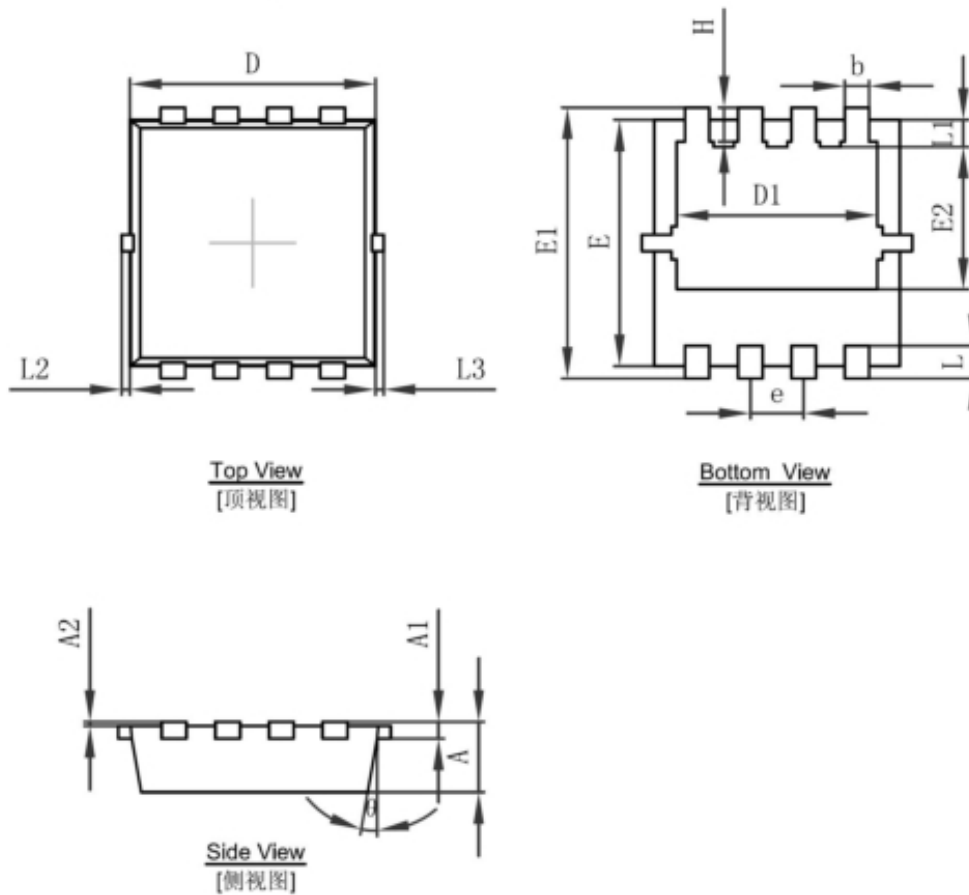


Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case

PDFNWB3.3×3.3-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°